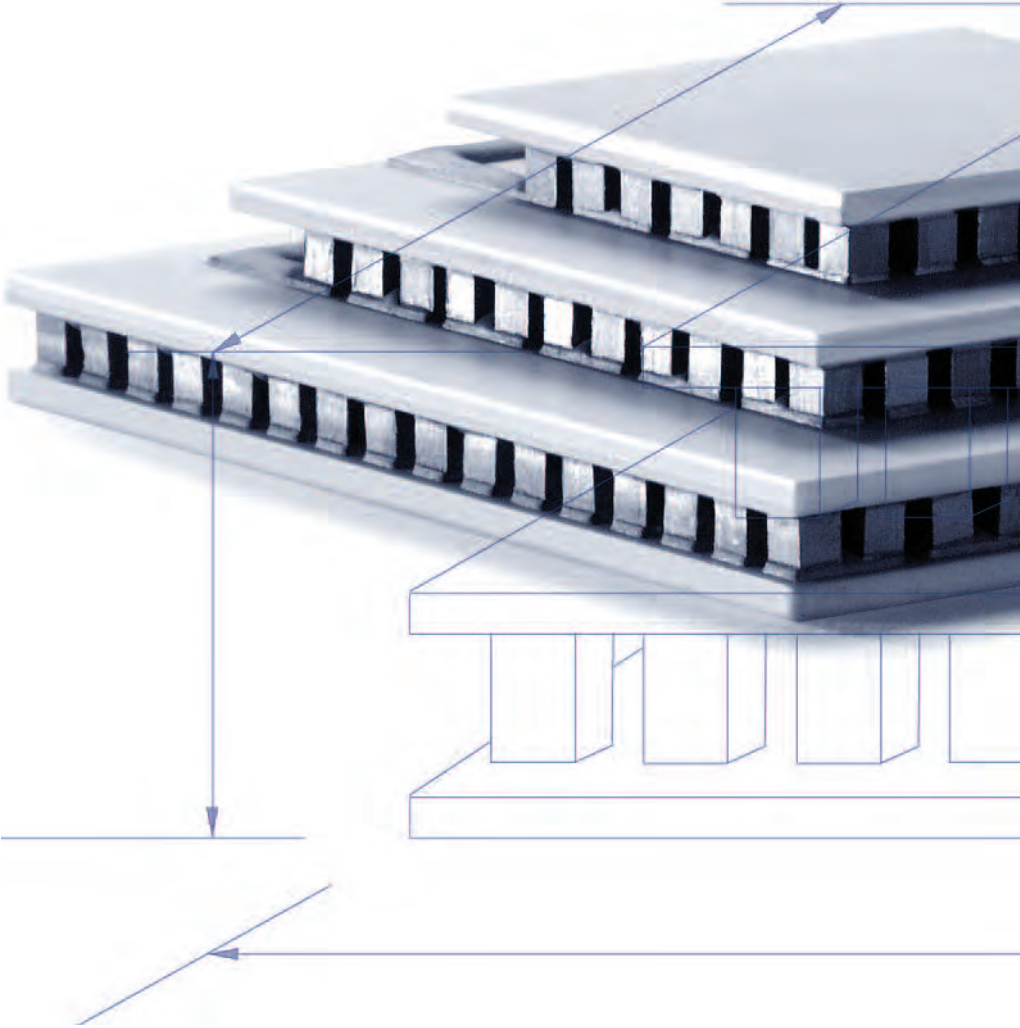


Thermoelectric
Modules



Thermoelectric Modules (TEMs)

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Ferrotec worldwide

Dear Customer,

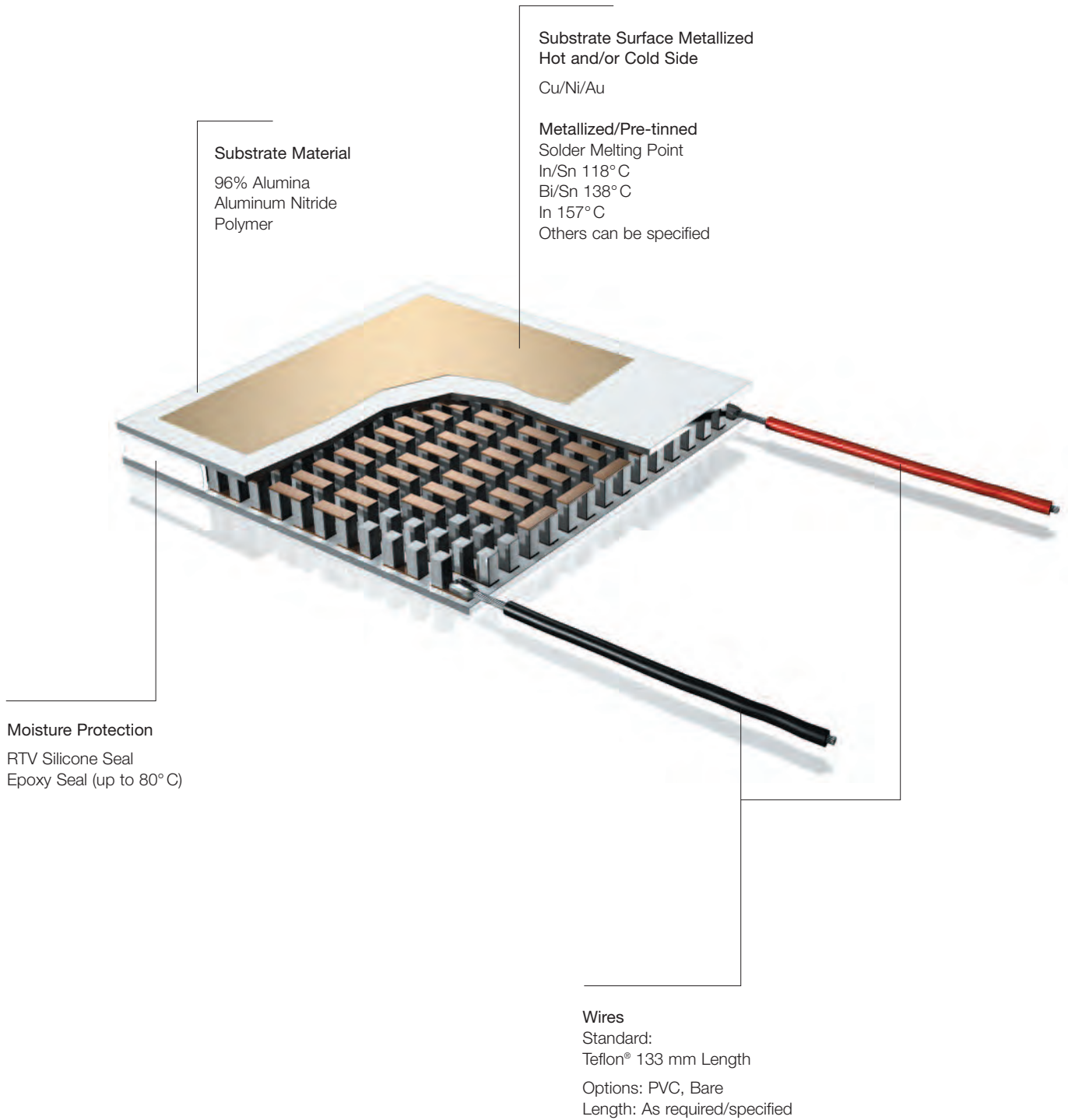
Thank you for your interest in Ferrotec thermoelectric products. Ferrotec, a manufacturer of thermoelectric modules and assemblies, was founded in the late 1980's and has continuously developed high quality products at competitive prices to serve the needs of today's businesses worldwide.

Ferrotec is recognized as one of the most reliable providers in a wide variety of market segments, with applications ranging from consumer products to precise temperature control systems. Our flexibility and expertise enable us to offer effective product solutions with short delivery times through our global sales channels.

Working closely with our customers as partners, Ferrotec also specializes in the development and manufacture of custom modules and assemblies. We are committed to providing strong technical support and service throughout your product design process and beyond.



With ISO 9001, ISO 14001 and ISO/TS 16949 accreditations, you can be assured of high quality with all Ferrotec products.



Technical Introduction

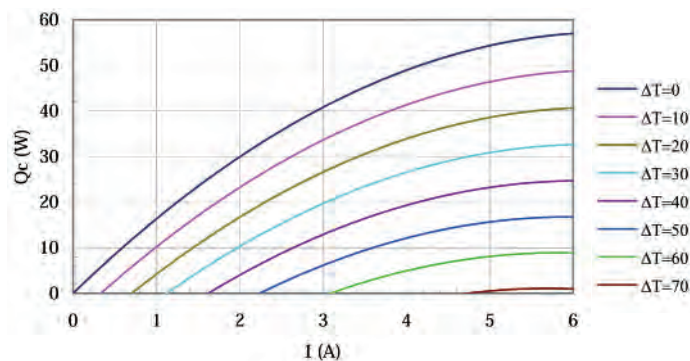
A thermoelectric module (TEM), also called a thermoelectric cooler or device, is a semiconductor based electronic component that functions as a compact and efficient heat pump. By applying a low voltage DC power source to a TEM, heat will be moved through the module from one side to the other. One module face, therefore, will be cooled while the opposite face simultaneously is heated. It is important to note that this phenomenon is fully reversible whereby a change in the polarity of the applied DC voltage will cause heat to be moved in the opposite direction. Consequently, a TEM may be used for both cooling and heating in a given application.

A TEM generally consists of two or more semiconductor elements, usually made of bismuth telluride (Bi_2Te_3), that are connected electrically in series and thermally in parallel. These thermoelectric elements and their interconnects typically are mounted between two thin metallized ceramic substrates, which provide structural integrity, insulate the elements electrically from external mounting surfaces, and provide flat and parallel contact surfaces.

Both n-type and p-type Bi_2Te_3 materials are used in a TEM. This arrangement causes heat to move through the cooler in one direction only while the electrical current moves back and forth alternately between the top and bottom substrates through each n-type and p-type element. The n-type material is doped to have an excess of electrons while the p-type material is doped to have a deficiency of electrons. The extra electrons in the n-material and the "holes" resulting from the deficiency of electrons in the p-material serve as carriers. These carriers move the heat energy through the thermoelectric material.

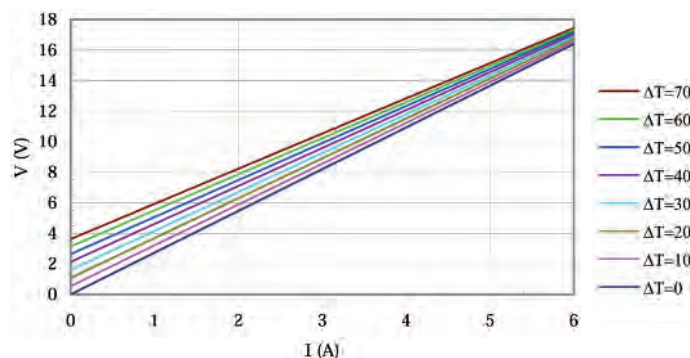
Heat flux – the heat actively pumped through the TEM – is proportional to the magnitude of the applied DC electric current. By regulating the input current from zero to maximum, one can adjust and precisely control the heat flow and module temperature differential.

Each application will have its own set of parameters that will impact the temperature of the TEM hot side (T_h). Performance data is presented graphically and there are four important attribute graphs explaining the TEM performance, e.g. TE 9500/127/060B ($T_h = 50^\circ\text{C}$).



Q_c vs. I

This graph shows the TEM's heat pumping capacity (Q_c) in watts at a fixed level of T_h as a function of input current (I) at various differential temperatures across the TEM (ΔT). This data allows the user to determine whether the module under consideration has sufficient heat removal capacity to meet the application requirements.



V vs. I

A graph of V vs. I depicts the voltage necessary to produce the current needed at various differential temperatures. If you have selected an appropriate TEM, established the correct operating current from the Q_c vs. I graph, and figured out the ΔT value, you can use this chart to determine the power supply requirements.

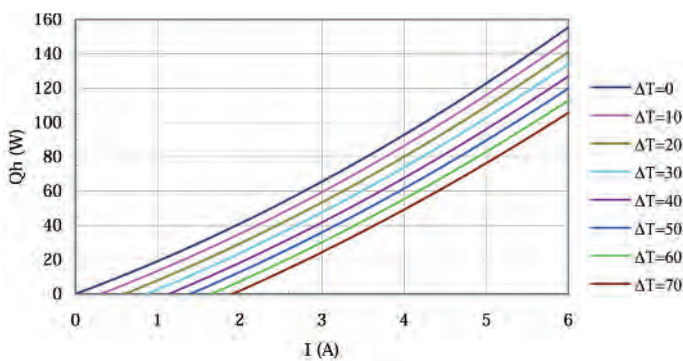
TEMs can be mounted in parallel to increase the heat transfer capacity, or they can be stacked in multistage cascades to increase the temperature differential.

TEMs have no moving parts, so they are reliable and virtually maintenance free. They are also smaller, lighter and quieter than comparable mechanical cooling systems. However, TEMs are not ideal for every cooling application, and there are situations in which a simple passive cooling device, such as a heat sink, is more appropriate. There are also situations in which thermoelectric cooling is the only suitable solution, or for which it presents significant advantages over other cooling methods.

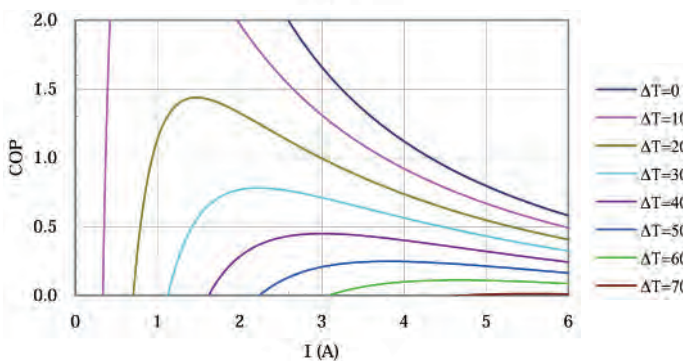
TEMs can provide active cooling, which means they cool below ambient temperature, which is not possible with heat sinks alone. Their solid-state construction ensures high reliability, which is an advantage when they are to be used in a system that is not easily accessible after installation. Operation is acoustically silent and electrical interference is negligible.

Selection of the proper TEM for a specific application requires an evaluation of the total system in which the TEM will be used. For most applications it should be possible to use a standard TEM configuration, while in certain cases a special design may be needed to meet stringent heat pumping, electrical, mechanical, or other design requirements. Although we encourage the use of a standard TEM whenever possible, Ferrotec specializes in the development and manufacture of custom TEMs. We will be pleased to provide technical analysis to define a unique TEM design that meets your requirements precisely.

Most cooling systems are dynamic in nature, and overall system performance is a function of several interrelated parameters. If there is any uncertainty about which TEM would be most suitable for a particular application, we recommend that you contact our sales team or your local representative for assistance.



Qh vs. I
The graph Q_h versus I above shows the expelled heat (Q_h) in watts, from the hot side of the TEM as a function of current level at a specific T_h level. The quantity Q_h is the sum of Q_c (cooling capacity) and $I \times V$ (electrical power in).



COP vs. I
This important graph relates the coefficient of performance (COP) and ΔT to input current. The COP is equal to the heat pumped divided by the input power. This graph enables the user to determine the coefficient of performance (efficiency) to maximize the cooling capacity and minimize the heat rejected to the heat sink.

Before starting the actual TEM selection process, the designer should be able to answer the following questions:



- At what temperature must the cooled object be maintained and to what precision?
- How much heat must be removed from the cooled object?
- What is the expected ambient temperature range? Will the temperature change significantly during operation?
- What is the thermal resistance of the heat sink (hot side) and what is the interface material to be used?
- What is the allowable footprint and height of the module?
- What DC power is available? What voltage and current restrictions exist?
- What is the expected temperature of the heat sink during operation? Is this temperature steady or variable?
- How will the TEMs be mounted?

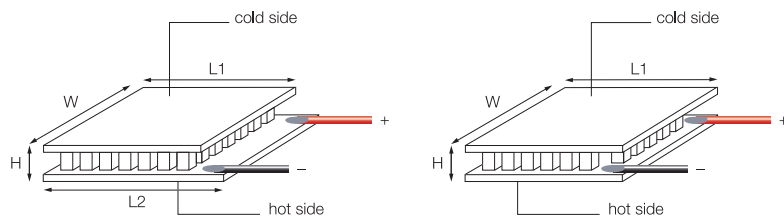
See the four graphs at the bottom of page 2 and 3.

Miniature Modules



The Miniature TEM series is suitable for various cooling and heating applications where only a small amount of heat is involved. Typical application areas include laser diode cooling, infrared systems, electro-optics and electronic equipment and other low wattage applications. Standard substrates are metallized (M) and gold-plated. These TEMs are also available with different configurations.

TEM Model No.	I _{max} (A)	V _{max} (V)	ΔT _{max} (°C)	Q _{cmax} (W)	Dimensions (mm)			
					W1	L1 (T1)	L2 (T2)	T (M)
9500/007/012 M	1.2	0.96	70	0.63	4.01	4.01	–	2.39
9502/017/012 M	1.2	2.3	70	1.5	6.05	6.05	–	2.65
9500/018/012 M	1.2	2.5	70	1.6	6.05	6.05	7.62	2.65
9503/018/012 M	1.2	2.5	70	1.6	6.05	6.20	7.19	2.14
9502/023/012 M	1.2	3.2	70	2.0	6.05	7.98	–	2.14
9502/029/012 M	1.2	4.0	70	2.6	6.05	9.91	–	2.14
9502/031/012 M	1.2	4.3	70	2.8	7.98	7.98	–	2.14
9502/065/012 M	1.2	8.9	70	5.8	12.10	11.20	–	2.65
9500/007/018 M	1.8	0.96	70	0.94	4.01	4.01	–	2.09
9502/017/018 M	1.8	2.3	70	2.3	6.05	6.05	–	2.34
9500/018/018 M	1.8	2.5	70	2.4	6.05	6.05	7.62	2.34
9503/018/018 M	1.8	2.5	70	2.4	6.05	6.20	7.19	1.64
9502/023/018 M	1.8	3.2	70	3.1	6.05	7.98	–	1.83
9502/029/018 M	1.8	4.0	70	3.9	6.05	9.91	–	1.83
9503/029/018 M	1.8	4.0	70	3.9	6.05	10.20	–	1.64
9502/031/018 M	1.8	4.3	70	4.1	7.98	7.98	–	1.83
9503/031/018 M	1.8	4.3	70	4.1	7.98	7.98	–	1.64
9503/035/018 M	1.8	4.8	70	4.7	6.05	12.20	–	1.64
9502/065/018 M	1.8	8.9	70	8.7	12.10	11.20	–	2.34
9503/018/020 M	2.0	2.5	70	2.6	6.05	6.20	7.19	1.64
9503/023/020 M	2.0	3.2	70	3.4	6.05	8.18	–	1.64
9503/029/020 M	2.0	4.0	70	4.3	6.05	10.20	–	1.64
9503/035/020 M	2.0	4.8	70	5.2	6.05	12.20	–	1.64
9503/035/025 M	2.5	4.8	70	6.5	6.05	12.20	–	1.64



Type 2 (T2) TEMs feature a “porch” for more accurate heat distribution. This makes the L2 dimensions slightly longer than the L1 dimension.

The following terms are used in the tables at T_{hot} = 50 °C:

- I_{max}** Maximum input current in amperes at Q_c = 0 and ΔT_{max}
- V_{max}** Maximum DC input voltage in volts at Q_c = 0 and I_{max}
- ΔT_{max}** Maximum temperature differential in °C at Q_c = 0 and I_{max}
- Q_{cmax}** Maximum heat pumping capacity in watts at I_{max} and ΔT = 0
- T_{hot}** Temperature of TEM hot side during operation



The Single-Stage TEM series is suitable for a wide range of various cooling and heating applications which require medium or high pumping capacity. Typical application areas include biomedical instruments, consumer products, industrial and electrical equipment as well as laboratory and scientific instruments. Standard substrates are lapped with ± 0.025 mm tolerance. These TEMs are also available with different configurations.

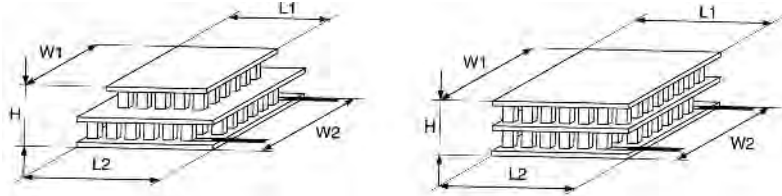


TEM Model No.	I _{max} (A)	V _{max} (V)	ΔT _{max} (°C)	Q _{cmax} (W)	Dimensions (mm)			
					W1	L1 (T1)	L2 (T2)	T
9501/017/030 B	3.0	2.3	72	3.8	11.5	11.5	–	3.18
9501/023/030 B	3.0	3.2	72	5.2	7.39	22.4	–	3.18
9501/031/030 B	3.0	4.3	72	7.0	15.1	15.1	–	3.18
9501/071/030 B	3.0	9.8	72	16.0	22.4	22.4	–	3.18
9501/127/030 B	3.0	17.5	72	29.0	29.7	29.7	–	3.94
9501/128/030 B	3.0	17.6	72	29.0	29.7	29.7	34.0	3.94
9501/017/040 B	4.0	2.3	72	5.1	11.5	11.5	–	3.18
9500/017/040 B	4.0	2.3	72	5.1	15.1	15.1	–	4.16
9501/023/040 B	4.0	3.2	72	6.9	7.39	22.4	–	3.18
9501/031/040 B	4.0	4.3	72	9.3	15.1	15.1	–	3.18
9500/031/040 B	4.0	4.3	72	9.3	20.0	20.0	–	4.16
9500/035/040 B	4.0	4.8	72	10.0	15.1	29.8	–	4.16
9501/063/040 B	4.0	8.7	72	18.0	20.1	39.7	–	4.16
9501/071/040 B	4.0	9.8	72	21.0	22.4	22.4	–	3.18
9500/071/040 B	4.0	9.8	72	21.0	29.8	29.8	–	4.16
9501/127/040 B	4.0	17.5	72	38.0	29.7	29.7	–	3.94
9500/127/040 B	4.0	17.5	72	38.0	39.7	39.7	–	4.16
9501/128/040 B	4.0	17.6	72	38.0	29.7	29.7	34.0	3.94
9500/128/040 B	4.0	17.6	72	38.0	39.7	39.7	42.8	4.16
9500/017/060 B	6.0	2.3	72	7.6	15.1	15.1	–	4.16
9500/031/060 B	6.0	4.3	72	14.0	20.0	20.0	–	4.16
9500/035/060 B	6.0	4.8	72	16.0	15.1	29.8	–	4.16
9500/071/060 B	6.0	9.8	72	32.0	29.8	29.8	–	4.16
9501/127/060 B	6.0	17.5	72	57.0	29.7	29.7	–	3.61
9500/127/060 B	6.0	17.5	72	57.0	39.7	39.7	–	4.16
9500/128/060 B	6.0	17.6	72	57.0	39.7	39.7	42.8	4.16
9500/017/085 B	8.5	2.3	72	11	15.1	15.1	–	3.94
9500/031/085 B	8.5	4.3	72	20	20.0	20.0	–	3.94
9500/035/085 B	8.5	4.8	72	22	15.1	29.8	–	3.94
9500/063/085 B	8.5	8.7	72	40	39.7	39.7	–	3.94
9500/071/085 B	8.5	9.8	72	45	29.8	29.8	–	3.94
9500/127/085 B	8.5	17.5	72	80	39.7	39.7	–	3.94
9500/128/085 B	8.5	17.6	72	80	39.7	39.7	42.8	3.94
9500/031/090 B	9.0	4.3	72	22	29.8	29.8	–	4.60
9500/071/090 B	9.0	9.8	72	47	29.8	29.8	–	3.94
9500/097/090 B	9.0	13.3	72	65	29.8	29.8	–	3.55
9501/063/100 B	10.0	8.7	72	47	20.1	39.7	–	3.64
9500/127/100 B	10.0	17.5	72	95	39.7	39.7	–	3.64
9504/071/120 B	12.0	9.8	72	63	40.1	40.1	–	4.65
9504/017/150 B	15.0	2.3	72	19	22.0	22.0	–	4.65
9500/031/150 B	15.0	4.3	72	35	29.8	29.8	–	4.60
9504/071/150 B	15.0	9.8	72	79	40.1	40.1	–	4.65
9504/031/240 B	24.0	4.3	72	55	39.7	39.7	–	4.62
9506/031/400 B	40.0	4.3	72	92	55.0	55.0	–	4.85

Multi-Stage Modules



The Multi-Stage TEM series is designed to provide significantly higher ΔT . These TEMs are suitable for low temperature applications where a small or medium cooling capacity is required. Typical application areas include IR-detectors, CCD arrays and electro-optics. These items are also available with different configurations in cascade designs to meet a range of deep cooling applications. They provide higher temperature differentials than obtainable with standard single stage TEMs.



TEM Model No.	I _{max} (A)	V _{max} (V)	ΔT _{max} (°C)	Q _{cmax} (W)	Dimensions (mm)					
					W1	W2	L1	L2	T	
2-Stage Modules										
9520/157/035 B	3.5	18.2	106	11	20.0	39.7	20.0	39.7	7.39	
9520/175/035 B	3.5	16.7	100	18	39.7	–	39.7	–	6.80	
9520/185/065 B	6.5	17.9	95	37	29.8	39.7	29.8	39.7	6.99	
9520/157/070 B	7.0	17.3	106	24	20.0	39.7	20.0	39.7	6.99	
9520/197/080 B	8.0	17.8	91	52	29.8	39.7	29.8	39.7	6.45	
9520/094/230 B	23.0	8.2	88	74	45.2	–	54.1	–	7.49	

TEM Model No.	I _{max} (A)	V _{max} (V)	ΔT _{max} (°C)	Q _{cmax} (W)	Dimensions (mm)						
					W1	W2	W3	L1	L2	L3	T
3-Stage Modules											
9530/119/045 B	4.5	8.6	111	9.7	15.2	20.0	29.8	15.2	20.0	29.8	9.65
9530/228/045 B	4.5	16.4	111	18.0	20.0	29.8	39.7	20.0	29.8	39.7	9.85
9530/228/060 B	6.0	18.3	111	22.0	20.0	29.8	39.7	20.0	29.8	39.7	9.15

Center-Hole Modules



The Center-Hole TEM series is suitable for various cooling and heating applications which generally require medium pumping capacity. Typical application areas include industrial and electrical equipment as well as laboratory and opto-electronics. Standard substrates are lapped with ± 0.025 mm tolerance. These TEMs are also available with different configurations.

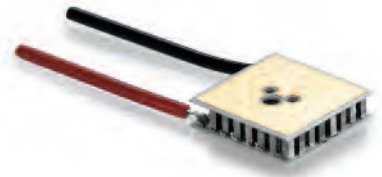
TEM Model No.	I _{max} (A)	V _{max} (V)	ΔT _{max} (°C)	Q _{cmax} (W)	Dimensions (mm)			
					W1	L1	D1	T
Square Type								
9508/023/030 B	3.0	3.2	72	5.2	15.1	15.1	5.0	3.18
9506/023/030 B	3.0	3.2	72	5.2	15.1	15.1	6.7	3.18
9504/023/030 B	3.0	3.2	72	5.2	18.0	18.0	8.0	3.18
9508/023/040 B	4.0	3.2	72	6.9	15.1	15.1	5.0	3.18
9506/023/040 B	4.0	3.2	72	6.9	15.1	15.1	6.7	3.18
9504/023/040 B	4.0	3.2	72	6.9	18.0	18.0	8.0	3.18
9504/125/060 B	6.0	17.2	72	56	39.7	39.7	4.7	3.75

TEM Model No.	I _{max} (A)	V _{max} (V)	ΔT _{max} (°C)	Q _{cmax} (W)	Dimensions (mm)		
					DO	DI	T
Round Type							
9506/014/060 B	6.0	1.9	72	6.2	26.0	14.0	3.31

All TEMs are
RoHS
compliant

Multi-Hole Modules

The Multi-Hole TEM series has been specifically designed for ø 5.6 mm CAN type laser diodes. The increased contact area between the TEM and laser diode package enables more uniform cooling with the target temperature being achieved more rapidly. The optimized thermal contact area results in very stable thermal performance for laser diodes. The standard series is available for laser diodes with diameters ranging from 3.5-9.0 mm. For other specific laser diode sizes or design requirements please contact Ferrotec.



TEM Model No.	I _{max} (A)	V _{max} (V)	ΔT _{max} (°C)	Q _{cmax} (W)	Dimensions (mm)		
					DO	DI	T
9507/023/012 M	1.2	3.2	70	2.0	8.65	8.65	2.14

High-Power Modules

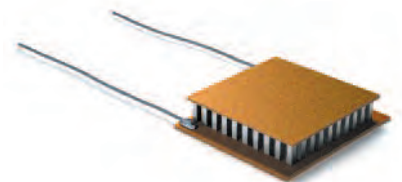
The High-Power TEM series is designed to maximize heat pumping capacity. The high density loading factor in these TEMs enables very high cooling capacities and efficiencies to be achieved in standard footprint sizes. The high cooling density enables high performing heat exchangers to be produced in smaller, more efficient sizes.



TEM Model No.	I _{max} (A)	V _{max} (V)	ΔT _{max} (°C)	Q _{cmax} (W)	Dimensions (mm)			
					W1	L1	L2	T
9500/241/060 B	6.0	33.1	72	108	55.0	55.0	-	4.16
9500/241/085 B	8.5	33.1	72	153	55.0	55.0	-	3.94
9500/391/085 B	8.5	53.8	72	248	55.0	55.0	-	3.35
9500/199/100 B	10.0	27.4	72	148	40.0	40.0	-	3.35
9500/241/100 B	10.0	33.1	72	180	55.0	55.0	-	3.64
9500/337/100 B	10.0	46.4	72	252	55.0	55.0	-	3.35
9500/127/120 B	12.0	17.5	72	114	39.7	39.7	-	3.45
9505/127/150 B	15.0	17.5	72	142	39.7	39.7	-	3.45
9500/131/150 B	15.0	18.0	72	147	30.0	60.0	-	3.45
9501/242/160 B	16.0	33.3	72	289	55.0	55.0	58.0	3.45
9506/031/600 B	60.0	4.3	72	139	55.0	55.0	-	4.85

Thin-Film Substrate Modules

The Thin-Film Substrate TEM series was specifically developed to offer greater design flexibility to users. Ferrotec Thin-Film Substrate modules can be rapidly prototyped in nearly any shape. Features such as internal thermistors or custom external metallization patterns can be easily added. The high performance polymer substrate is also available in many sizes.



TEM Model No.	I _{max} (A)	V _{max} (V)	ΔT _{max} (°C)	Q _{cmax} (W)	Dimensions (mm)			
					W1	L1	L2	T
9500/018/012 MP	1.2	2.5	66	1.3	6.05	6.05	7.62	2.09
9502/031/012 MP	1.2	4.3	66	2.3	7.98	7.98	-	2.09
9502/065/012 MP	1.2	8.9	66	4.8	12.10	11.20	-	2.09
9500/018/018 MP	1.8	2.5	66	1.9	6.05	6.05	7.62	1.79
9502/031/018 MP	1.8	4.3	66	3.4	7.98	7.98	-	1.79
9502/065/018 MP	1.8	8.9	66	7.2	12.10	11.20	-	1.79

Thermal Cycling Modules



Ferrotec's 70-series has been specifically designed for cycling applications. Tests show TEM life time is significantly greater than a standard module under the same thermal cycling conditions. Typical application areas include instrumentation, chillers, PCR cyclers and analyzers. These TEMs are also available with different configurations.

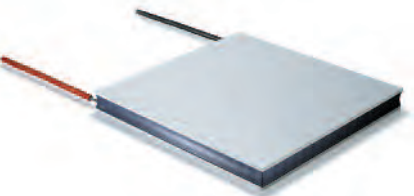
TEM Model No.	I _{max} (A)	V _{max} (V)	ΔT _{max} (°C)	Q _{cmax} (W)	Dimensions (mm)		
					W1	L1	T
7001/127/040 B	4.0	17.5	72	34	29.7	29.7	3.94
7000/127/060 B	6.0	17.5	72	51	39.7	39.7	4.16
7000/127/085 B	8.5	17.5	72	72	39.7	39.7	3.94
7000/031/150 B	15.0	4.3	72	31	29.8	29.8	4.60
7004/071/150 B	15.0	9.8	72	71	40.1	40.1	4.65
7004/031/240 B	24.0	4.3	72	49	39.7	39.7	4.62

TEM Option: RTV Silicone Seal



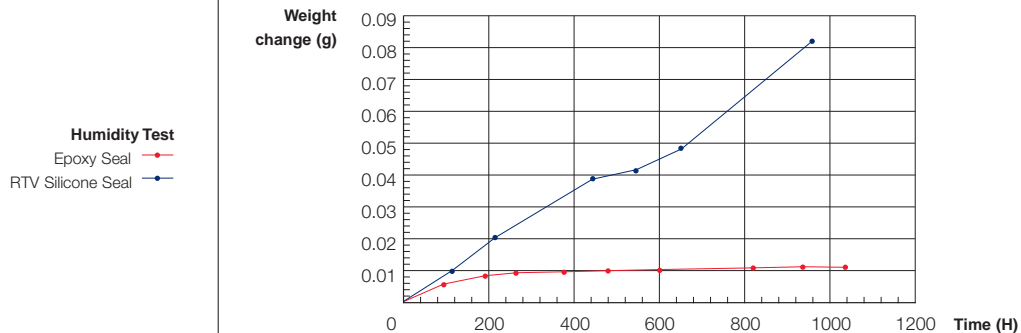
Ferrotec offers an electronics-grade silicone as an option for perimeter sealing TEMs. This RTV Silicone Seal is an effective barrier against condensation when operating TEMs below the dew point. Continual moisture contact within the TEM can lead to performance degradation. The RTV Silicone Seal is flexible after setting and retains its elasticity over time, this property is particularly useful in rigorous, temperature cycling applications. Ferrotec RTV Silicone Seal is effective over a temperature range of -60° C to +200° C. The impact of the RTV Silicone Seal on cooling performance is depending on the design of the assembly.

TEM Option: Epoxy Seal



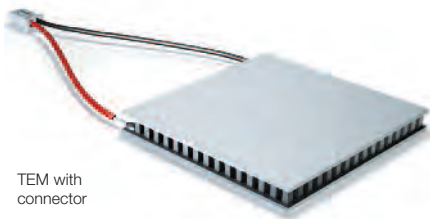
Epoxy sealing is offered for protecting TEMs used in high humidity environments. Although RTV silicone sealing has been demonstrated to be an effective moisture barrier, our epoxy sealant offers greater moisture resistance for those applications requiring the highest protection.

Ferrotec has carefully screened and tested many epoxy types to develop the most effective solution for TEMs. Brittleness is a common problem with some epoxies used to seal TEMs, and it can lead to separation from the substrate over time and cause loss of seal. Ferrotec epoxy sealant forms a strong bond with the substrate and remains flexible after curing, therefore avoiding this common problem. Ferrotec epoxy sealant can be applied to nearly all TEM types. The impact of the epoxy on cooling performance is depending on the design of the assembly.

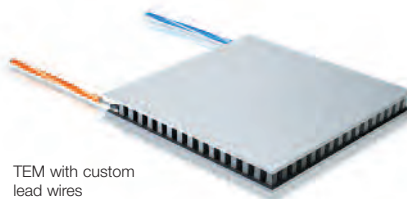


Extensive testing has demonstrated that epoxy sealant outperforms standard RTV silicone sealant in terms of moisture protection. The graph above shows the weight gain in a typical TEM exposed to a high humidity environment. The weight gain with the RTV silicone sealant is relatively small, but is nearly negligible with the epoxy sealant. Ferrotec epoxy has also demonstrated very good resistance to humidity under aggressive thermal cycling testing. The electrical resistance of this epoxy is high, in the M-ohm range. The maximum recommended operating temperature for the epoxy sealant is 80° C.

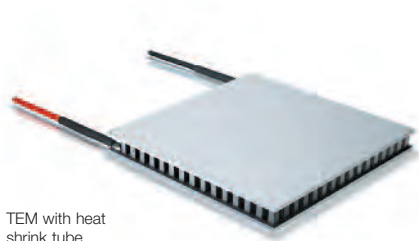
Ferrotec can offer modifications for a complete custom designed TEM, in terms of size, shape, substrate materials or metallization. Please contact Ferrotec with your specific design requirements.



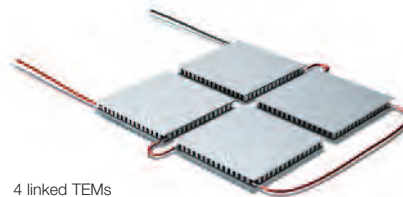
TEM with connector



TEM with custom lead wires



TEM with heat shrink tube



4 linked TEMs

The FTD001 is a demonstration product, which exhibits the Peltier effect of TEMs (it demonstrates both cooling and heating).

Quick Response: The efficient design results in quick response times when power is applied.

Compact Design: The assembly is efficient and compact based on a high performance heat sink and DC fan. DC power is delivered to the module by a small AC/DC adaptor.

Bi-Directional Operating: Both heating and cooling modes are selectable. A single switch allows selection of either heating or cooling modes.

Safe Design: The single, two-way switch uses a momentary contact in the heating direction to avoid excessive module temperatures and reduce the risk of burns.

Easy Operation: The assembly only requires plugging in the attached AC/DC adaptor, and then flipping (or holding) a single switch to either heat or cool the thermoelectric surface.

TEM Demonstration Kit: FTD001



Thermoelectric Solutions for Precision Thermal Management

TEM Standard Assembly: FTA951



The FTA951 is an easy to mount standard cold plate assembly, suitable as a building set for all kinds of cooling and heating applications.

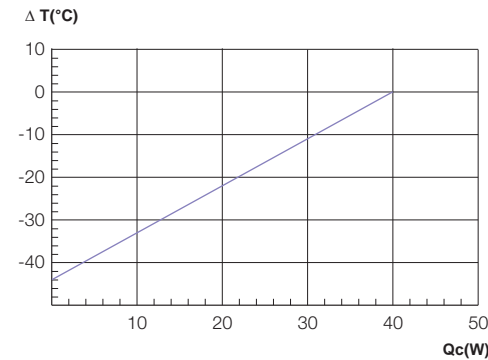
Features

1. Includes a unique airtight sealing structure which minimizes moisture permeation.
2. Cooling performance is optimized through the use of a high efficiency heat sink.
3. The assembly design isolates the TEM from shock and vibrations, increasing reliability.
4. The assembly includes a high reliability DC fan to ease integration with existing equipment.
5. With several unique features in this assembly design, a patent is pending.

Examples of Typical Applications

Compact Refrigerators, Cooled/Heated Compact Cases, Testing Stands, Dehumidifiers, Scientific Instrumentation and others.

Performance



$\Delta T = T_c - T_a$ (°C)
 T_a = Ambient temperature
 T_c = The temperature of the TEM Standard Assembly surface

Specification

TEM Model No.	V (V)	I (A)	I _{max} (A)	Q _{cmax} (W)	Dimensions (mm) W x L x H	Dim. Cooling Plate (mm) W x L
FTA951	12 (DC)	5.8	7.0	39	122 x 100 x 102	80 x 80

V = Rated Voltage (V) DC Fan Rated Voltage/Current = DC12/0.39 A
 I = Rated Current (A) Ambient Temp.: $T_a = 25^\circ\text{C}$, Cooling Block Temp.: $T_c = 25^\circ\text{C}$
 I_{max} = Maximum Current (A) Temp. Differential ($T_a = T_h = T_c$), $T_a = 25^\circ\text{C}$, Heat sink Temp.: T_h
 Q_c = Heat Pumping Capacity (W) Ambient Temp.: $T_a = 25^\circ\text{C}$, Cooling Block Temp.: $T_c = 25^\circ\text{C}$

The figures seen in the above performance table chart reflect average values.

Testing was performed with the cooling plate surrounded by insulation.

The dimensions do not include the side terminal. Mechanical drawing available on request.

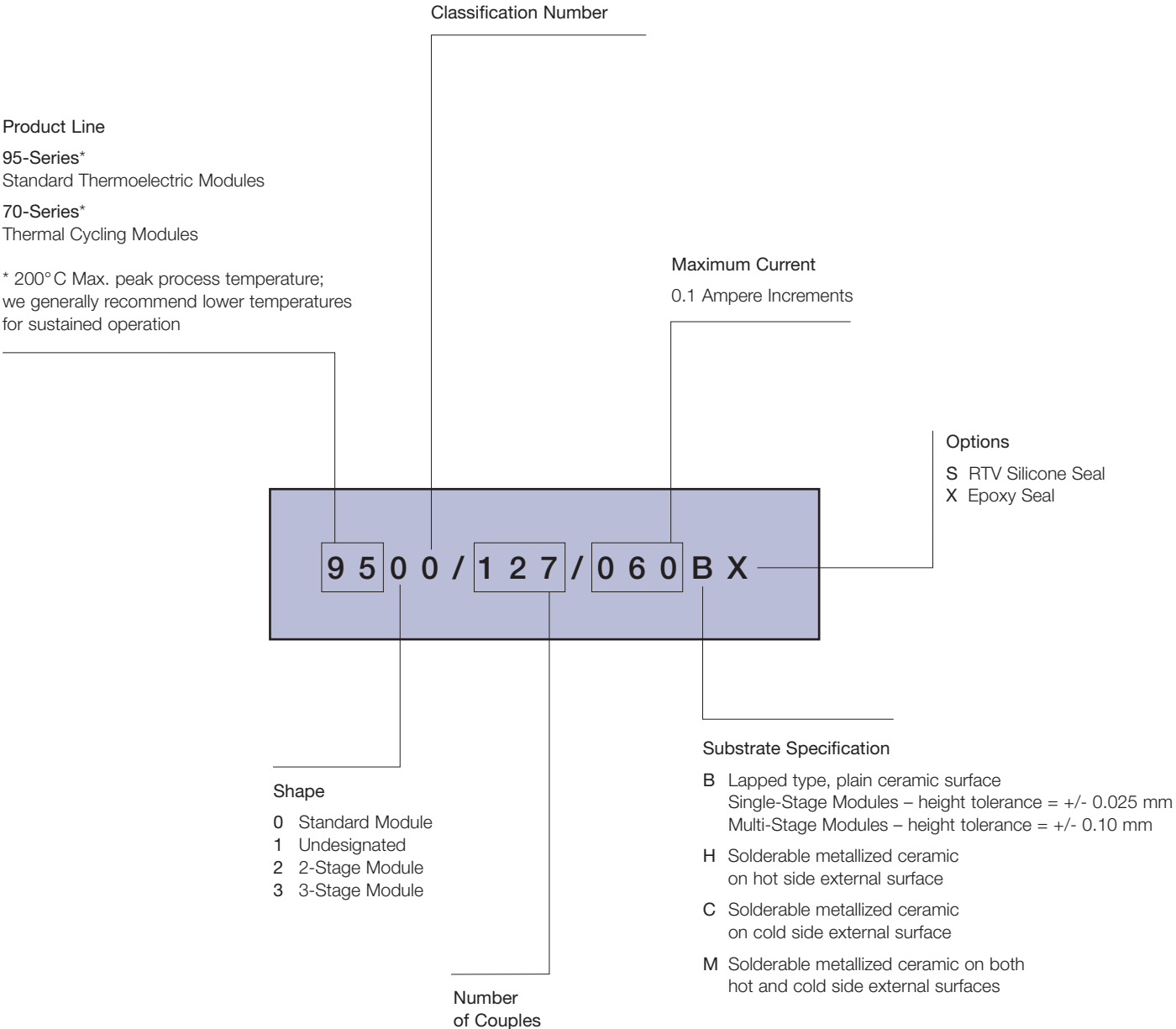
The standard configuration includes a heat insulation package.

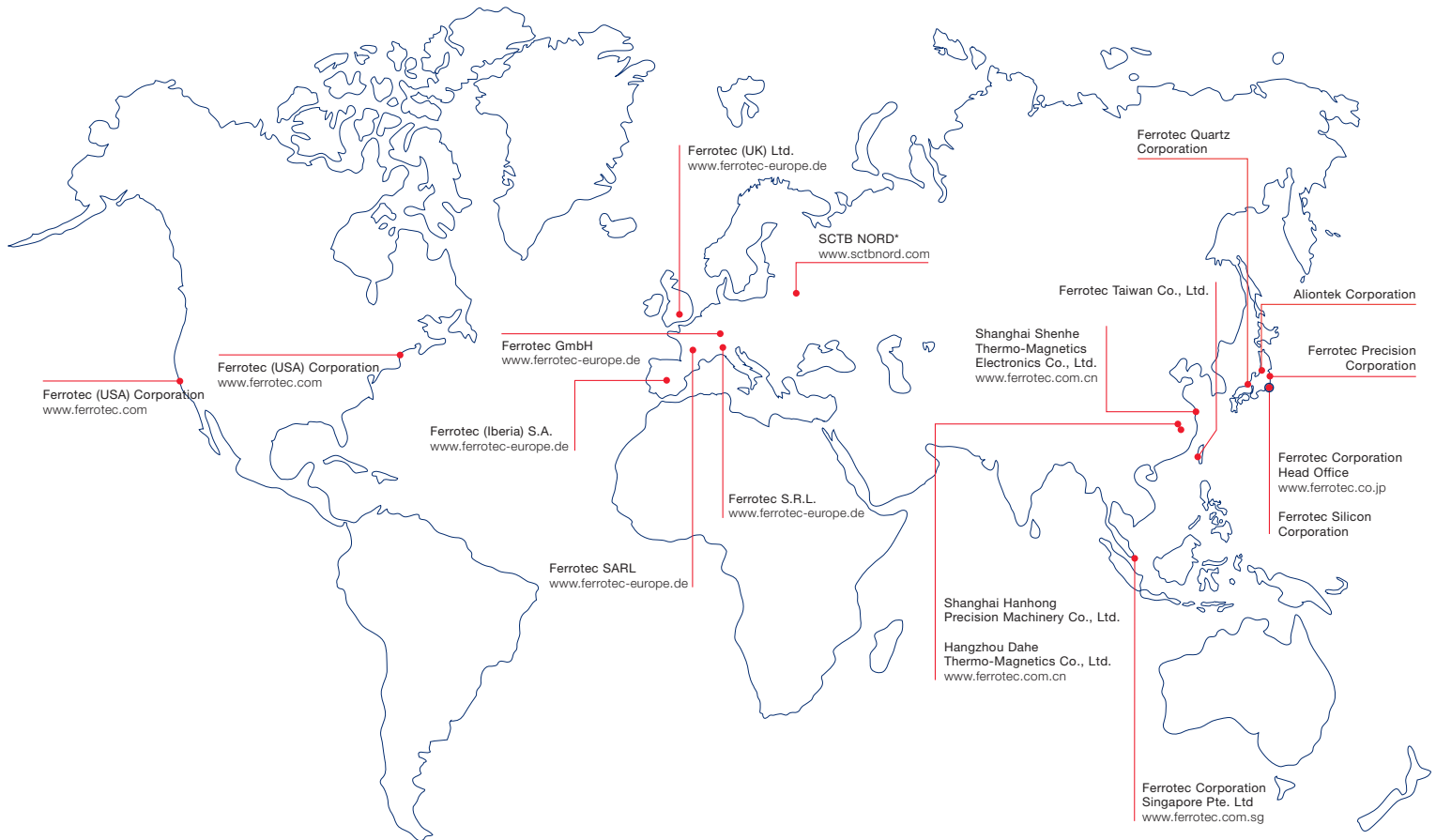
The maximum recommended operating temperature range is from 0°C to 80°C.

TEM Customized Assemblies



Ferrotec offers custom design options for a range of TEM based assemblies. Our assembly solutions are carefully designed and employ high-quality components, which provide the best combination of performance and economy. We work closely with our customers to verify that their design objectives are met and that a cost-effective manufacturing solution is available to them. We encourage you to contact us with your heat management need, so that we can assist you in designing a custom TEM based assembly.





* SCTB NORD (Russia), a top class TEM manufacturer, focused mainly on high performance and High Reliability TEMs, was merged into the „Ferrotec Group“ in August 2005.

Applications of TEMs

For example:

Automotive

Heated and cooled seats

Semiconductor

Chiller
Circulator
Cooling plate / chuck

Biomedical

Blood analyzer
PCR
Specimen temperature cycling

Scientific

Circulator
Dehumidifier
Spectrophotometer

Optical

Charged couple device (CCD) cooling
Infrared detectors
Laser diode cooling
Photo diode cooling
SHG laser cooling

Computer

CPU Cooling
Chip-set burn-in

Consumer

Cooler box
Mini refrigerator
Beverage cooler / heater
Wine cooler

Industrial / Commercial

Waste heat power generation
Remote power generation

Please contact us using the Customer Request Form

Ferrotec reserve the right to amend product design and specification without prior notice. Subject to alteration. Errors and misprints excepted.



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